Company Profile

Version : 13.10

Alti high-tech Introduction

Introduction

<table>
<tr><td>Company</td><td colspan="4">㈜ 알티하이텍, alti hightech Co., Ltd.
(100% subsidiary of “DSK Co., Ltd.”, a listed company on KOSDAQ)</td></tr>
<tr><td>Establishment</td><td>JUL. 2007</td><td rowspan="3">business product</td><td rowspan="3"><Laser System & Sub-System>
· Peed Off System
· WBG Tape LAMI & Laser Cutting
· Large Area Glass Cut
· Marking System(IR / GR / UV)
· ITO Patterning
· Secondary Battery Separator Cutting</td><td rowspan="3"><Laser Source>
· Solid-state Laser
· Gas Laser
· Fiber Laser
· Semiconductor Laser</td></tr>
<tr><td>Employee</td><td>11 Persons (2023/01) / engineer share73%</td></tr>
<tr><td>Location</td><td>3F, 710 Suin-ro, Sangnok-gu, Ansan-si, Gyeonggi-do, Korea</td></tr>
<tr><td>CEO</td><td>TG Kim.</td><td>Export Country</td><td colspan="2">China, Vietnam, Malaysia, Poland, Singapore</td></tr>
<tr><td>Capital</td><td>350,000,000KRW</td><td>Home Page</td><td colspan="2">www.alti-ht.com</td></tr>
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Major suppliers and performance

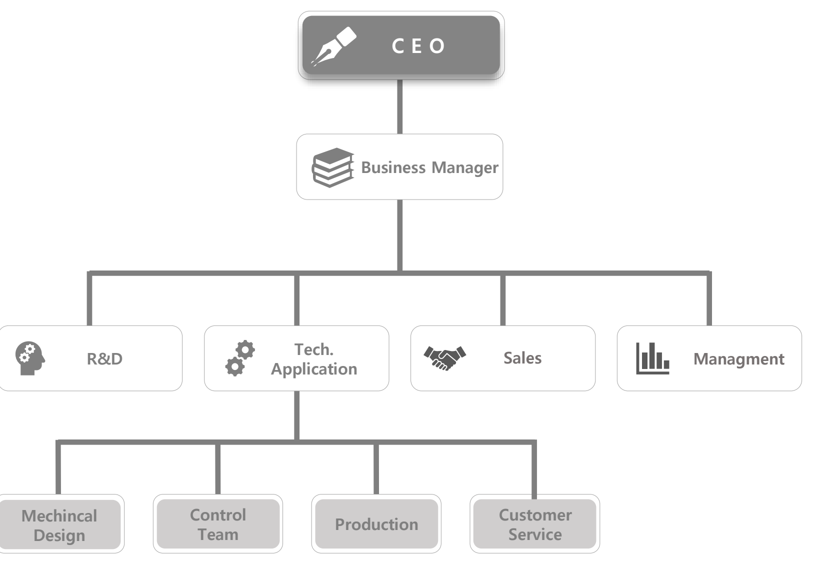
- Laser Marker 200 set : Company “LG*” Domestic (Paju, Gumi), China, Vienam, etc
- Secondary Battery Laser Cutting System 6 line : Company “LG**”
- Peed Off System 4 line : Company “J****”, Company “M****”
- Green Laser, Fiber Laser ... : Performance of supply to many domestic companies

CE certification

Corporate affiliated research institute

Factory Registration

Organization chart and Major History



Year	Month	Event
2007	07	Establishment of a corporation
	12	Release the Side Pumped IR 100W, Green 50W Laser
2008	06	Release the Side Pumped IR 200W, Green 100W Laser
2009	04	Release the End Pumped IR 10W, Green 5W Laser
2010	06	Release the End Pumped IR 20W, Green 10W Laser
2011	06	Join DSK., Co. Ltd. as subsidiaries
	08	Acquired product CE certification : TUV
2011	09	National Project – Release the Photonic Crystal Fiber Laser System
2014	03	LGD Smart Phone Production line
2015	03	LGD Smart Phone Production line
	05	LGD Laptop Production line
2016	02	LGD Smart Phone Production line
2017	01	LGD Laptop Production line
	02	LGD Smart Phone Production line D818, E52
2018	05	BOE Smart Phone Production line
2019	01	LGD Smart Phone Production line E62
2020	10	LGD Smart Phone Production line E63
2021	09	LGES Secondary Battery Separator Laser Cutting Module
2022	03	LGD Smart Phone Production line

Alti high-tech Introduction

Alti hightech is founded in 2007 and merged into DSK in 2011 as 100% subsidiary. Alti hightech is a technology oriented company that specializes in Laser related technology, products and businesses from Laser source to variety of laser applications.

Side Pumping IR/Green Laser

AHT-SS060 Series
AHT-SS100 Series
AHT-SS200M
AHT-SG030 Series
AHT-SG050 Series
AHT-SG100M

End Pumping IR/Green Laser

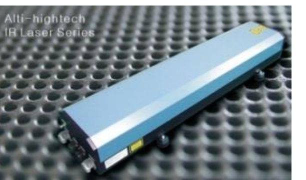
AHT-SE010T
AHT-SK005T

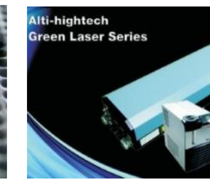
Industrial Laser Marking

High beam quality and stability
Easy integration and service
Compact, air-cooled design
Remote control interfaces
Optimized performance for your application

Laser System

Peel Off System
Wafer BG Tape Free LAMI & Laser Cut System
Large Area Glass Cut(MotF)
Secondary Battery Separator Cutting(Module)



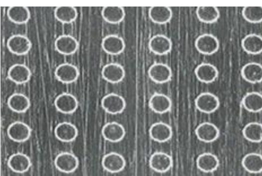


FPCB Marking

PS Marking

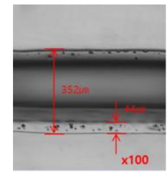
Paper Marking

Glass Ink Coating Surface Marking

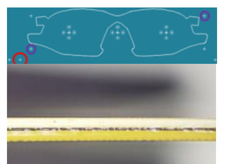


SUS Plate Texturing

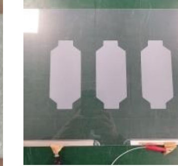
Peel Off System



Wafer BG Tape LAMI & Laser Cut

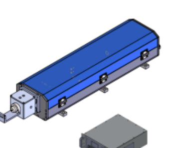


Laser Area Film / Glass Cut



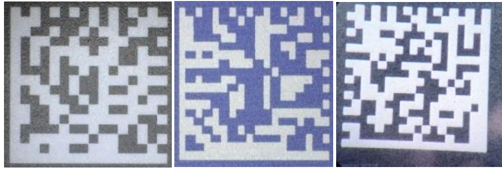
ITO Patterning

Laser Business Area



Laser Source & Optical Solutions

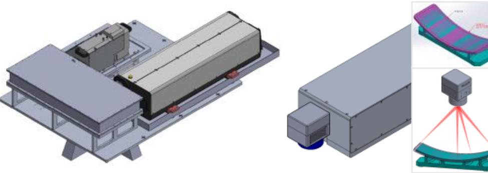
· Solid-state Laser
· Gas & Liquid Laser
· Fiber Laser
· Semiconductor Laser

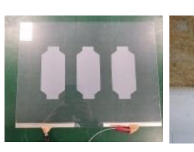


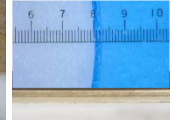
alti hightech

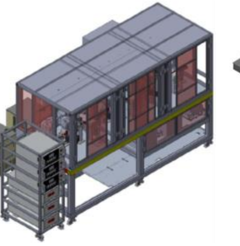
Laser Sub-System / Modules

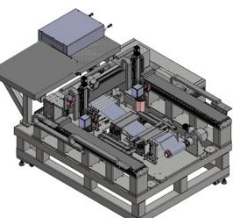
· ITO Patterning Module
· 3D Film Cutting Module
· Wafer BG Tape Free LAMI
  & Laser Cutting System
· Marking Module
. Clear Polymer Welding Module

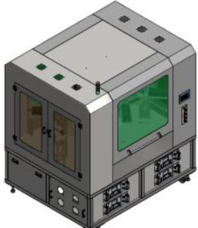


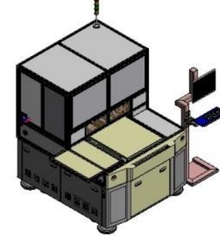






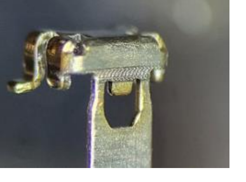


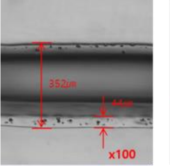


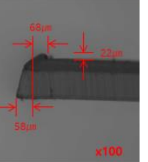


Laser System

· Peel Off System
· Wafer BG Tape Free LAMI
  & Laser Cutting System
. Large Area Glass Cut(MotF)
· Marking System (IR / GR / UV)





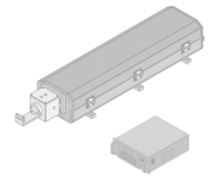


CATALOG

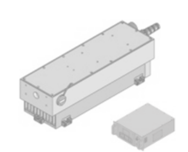
Technology of Alti-hightech

< Product Line -Up>

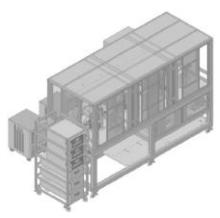
- Peel Off System
- Wafer BG Tape Free LAMI
  & Laser Cutting System
- Marking System(IR / GR / UV)
- Large Area Film or Glass Cut(MotF)



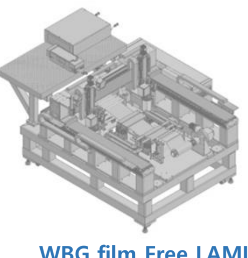
Side Pumped



End Pumped



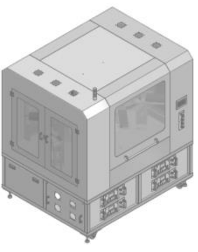
Peel Off System



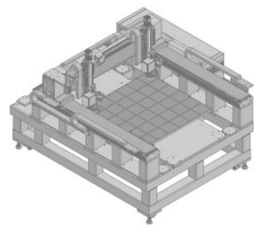
WBG film Free LAMI
& Laser Cut System

<Laser Sub-System / Modules>

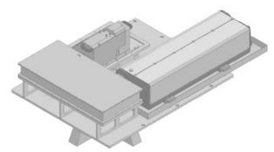
- Secondary Battery Separator Cutting
- ITO Patterning
- 3D Film Cutting
- Marking Module (IR / GR / UV)
- Clear Polymer Welding Module
- Coaxial Vision Module



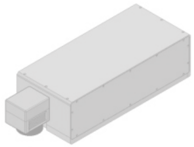
Marking System



Large Area Glass
or Film Cut(MotF)

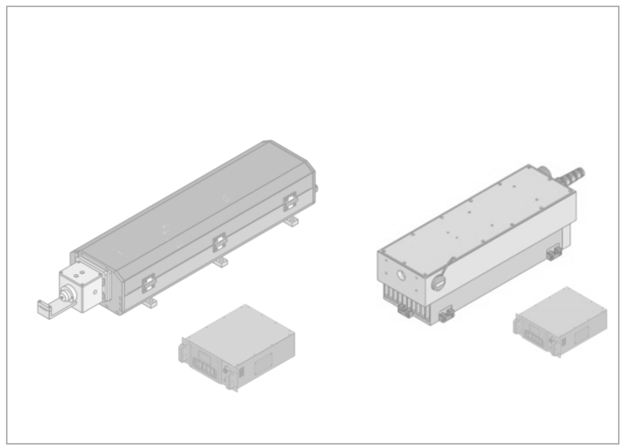


Secondary Battery Separator
Cutting Module



Marking Module

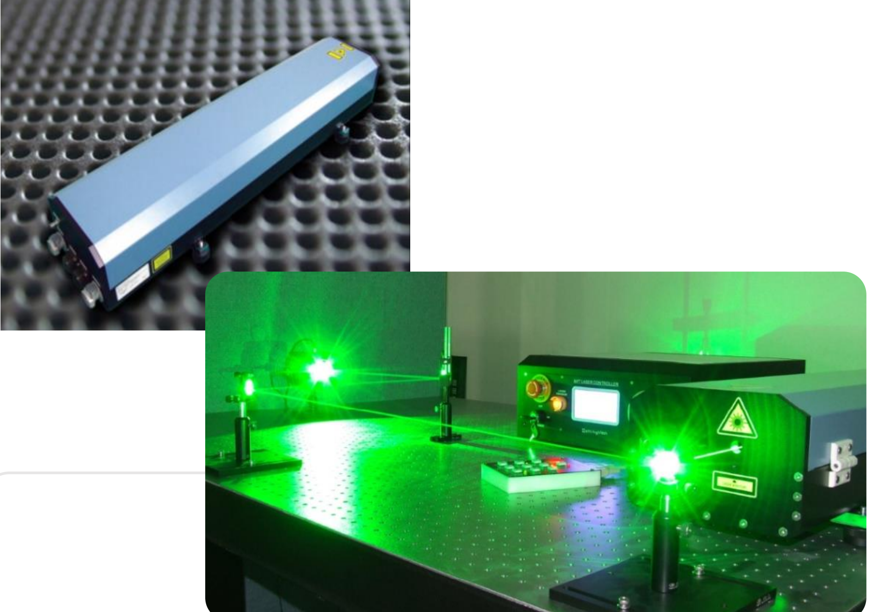
LASER SOURCE



Laser Source(Side Pumped) - Introduction

alti hightech

- High Pulse Energy → Capable of responding to high power laser applications
- Adjustment function such as Beam Mode and Pulse Energy that can be optimized for application
- IR/GR/UV Wavlength Products → Capable of responding to various output wavelengths
- S/W remote control → Laser Status Monitoring
- 24/7 operation possible by securing Long Term stability



Laser(IR) Key Specification

Technical Data	Industrial DPSS Laser / Solid-State, Side Pumped Laser		
Model	SPL-SS060x-01	SPL-SS100x-01	SPL-SS200M-01
System Specifications			
Wavelength [nm]	1,064	1,064	1,064
Average power [W]	60 @ 10kHz	100 @ 10kHz	200 @ 10kHz
Repetition rate range [kHz]	Single Shot ~ 50 kHz		
Pulse width [ns]	< 200 @ 10kHz	< 200 @ 10kHz	< 200 @ 10kHz
Spatial mode	TEM_{00} ~ MM	TEM_{00} ~ MM	MM
M^2	1.1 ~ 15	1.1 ~ 15	~ 25
Energy per pulse [mJ]	6 @ 10kHz	10 @ 10kHz	20 @ 10kHz
Long term stability(>8Hr)[%]	< 1	< 1	< 1
P to p stability [% rms]	< 5	< 5	< 5
Polarization	Random	Random	Random
Warranty	12 Month	12 Month	12 Month
Environmental Specifications			
Operating Conditions			
Warm up time [min]	< 10	< 10	< 10
Temperature [℃]	15 ~ 35	15 ~ 35	15 ~ 35
Humidity [%]	10 ~ 90	10 ~ 90	10 ~ 90
Cooling	Closed Loop Water Cooling	Closed Loop Water Cooling	Closed Loop Water Cooling
Non-Operating Conditions			
Temperature [℃]	5 ~ 50	5 ~ 50	5 ~ 50
Humidity [%]	10 ~ 90	10 ~ 90	10 ~ 90
Controller Specifications			
External control	RS-232 Interface, TTL	RS-232 Interface, TTL	RS-232 Interface, TTL
Voltage	220VAC 60Hz	220VAC 60Hz	220VAC 60Hz
Power consumption max.	2.2kW(3.806kW with chiller)		

Laser Source(Side Pumped) - Specification

Green Laser Key Specification

Technical Data	Industrial DPSS Laser / Solid-State, Side Pumped Laser		
Model	SPL-SG030x-01	SPL-SG050x-01	SPL-SG100M-01
System Specifications			
Wavelength [nm]	532	532	532
Average power [W]	30 @ 10kHz	50 @ 10kHz	100 @ 10kHz
Repetition rate range [kHz]	Single Shot ~ 50 kHz		
Pulse width [ns]	< 200 @ 10kHz	< 200 @ 10kHz	< 200 @ 10kHz
Spatial mode	Low Order Mode ~ MM	Low Order Mode ~ MM	MM
M^2	5 ~ 10	5 ~ 15	~ 15
Energy per pulse [mJ]	3 @ 10kHz	5 @ 10kHz	10 @ 10kHz
Long term stability(>8Hrs) [% rms]	< 1	< 1	< 1
Pulse to pulse stability [% rms]	< 5	< 5	< 5
Polarization	Linear	Linear	Linear
Warranty	12 Month	12 Month	12 Month
Environmental Specifications			
Operating Conditions			
Warm up time [min]	< 20	< 20	< 20
Temperature [℃]	15 ~ 35	15 ~ 35	15 ~ 35
Humidity [%]	10 ~ 90	10 ~ 90	10 ~ 90
Cooling	Closed Loop Water Cooling	Closed Loop Water Cooling	Closed Loop Water Cooling
Non-Operating Conditions			
Temperature [℃]	5 ~ 50	5 ~ 50	5 ~ 50
Humidity [%]	10 ~ 90	10 ~ 90	10 ~ 90
Controller Specifications			
External control	RS-232 Interface, TTL	RS-232 Interface, TTL	RS-232 Interface, TTL
Voltage	220VAC 60Hz	220VAC 60Hz	220VAC 60Hz
Power consumption max.	2.2kW(3.806kW with chiller)	2.2kW(3.806kW with chiller)	2.2kW(3.806kW with chiller)

Laser Source(End Pumped) - Introduction

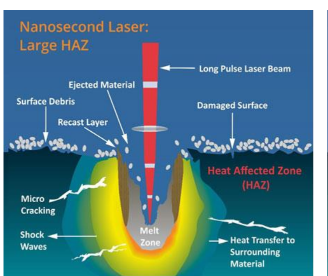
- TEM00 mode for most industrial needs such as precision marking and micromachining
- IR/GR/UV Wavlength Products → Capable of responding to various output wavelengths
- Sealed structure and downsizing design
- S/W remote control → Laser Status Monitoring
- 24/7 operation possible by securing Long Term stability

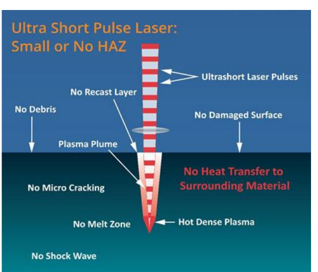
Laser Key Specification

Technical Data	Industrial DPSS Laser / Solid-State, End Pumped Laser		
Model	EPL-SS020T	EPL-SG005T	SPL-SU002T
System Specifications			
Wavelength [nm]	1064	532	355
Average power [W]	20 @ 30kHz	5 @ 30kHz	2 @ 30kHz
Repetition rate range [kHz]	Single Shot ~ 100 kHz		
Pulse width [ns]	< 20 @ 30kHz	< 17 @ 30kHz	< 15 @ 30kHz
Spatial mode	TEM00		
M^2	<1.2	<1.5	<1.5
Energy per pulse [uJ]	650 @ 30kHz	160 @ 30kHz	65 @ 30kHz
Long term stability(>8Hr) [%]	< 1	< 1	< 1
Pulse to pulse stability [% rms]	< 5	< 5	< 5
Polarization	Linear	Linear	Linear
Warranty	12 Month	12 Month	12 Month
Environmental Specifications			
Operating Conditions			
Warm up time [min]	< 5	< 15	< 20
Temperature [℃]	15 ~ 35		
Humidity [%]	10 ~ 90		
Cooling	Forced Air Cool (Water Cool Option)		
Non-Operating Conditions			
Temperature [℃]	5 ~ 45		
Humidity [%]	10 ~ 80		
Controller Specifications			
External control	RS-232 Interface, TTL		

Laser Source(Picosecond Laser) – Introduction (Scheduled for release in 2024)

- All fiber based Ultra Short Pulses Laser Source
- Stable Mode locked Master Oscillator
- <10ps Ultra Short Pulse Width Laser
- Variable pulse picker – Pulse on demand available

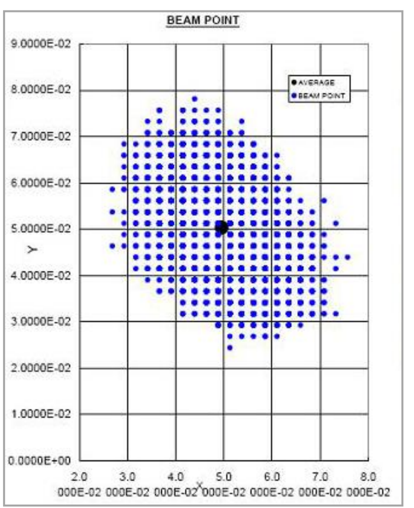




Laser Key Specification

Technical Data	Industrial DPSS Laser / Solid-State, End Pumped Laser		
Model	FPL-MO001T	FPL-SS010T	FPL-SG005T
System Specifications			
Wavelength [nm]	1030	1030	515
Average power [W]	50mW @ 50MHz	10W @ 1MHz	5W @ 1MHz
Repetition rate range [kHz]	Single Shot ~ 2 MHz		
Pulse width [ps]	< 10ps	< 10ps	< 10ps
Spatial mode	TEM00		
M^2	<1.2	<1.2	<1.5
Long term stability(>8Hr) [%]	< 1		
Pulse to pulse stability [% rms]	< 3		< 5
Polarization	Linear	Linear	Linear
Warranty	12 Month	12 Month	12 Month
Environmental Specifications			
Operating Conditions			
Warm up time [min]	< 5	< 5	< 20
Temperature [℃]	15 ~ 35		
Humidity [%]	10 ~ 90		
Cooling	Closed Loop Water Cool (Forced Air Cool – Option)		
Non-Operating Conditions			
Temperature [℃]	5 ~ 45		
Humidity [%]	10 ~ 80		
Controller Specifications			
External control	RS-232 Interface, TTL		

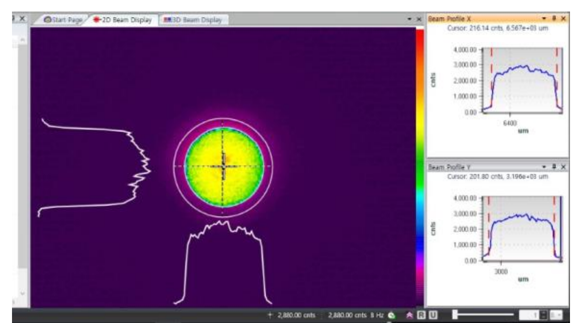
Laser Source - Stability

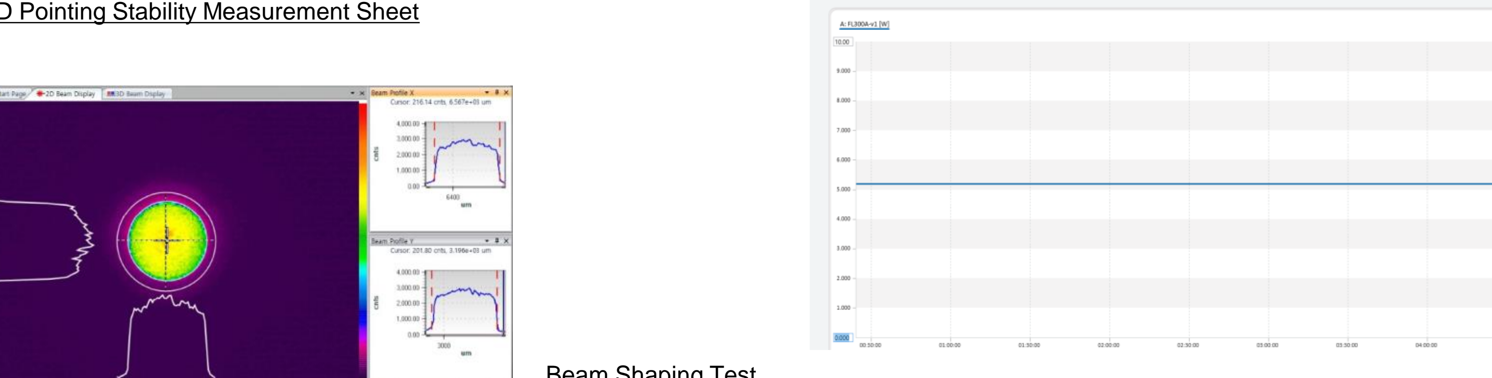


Beam 2D Pointing Stability Measurement Sheet

Beam Propagation Image

Measured Pulse Stability

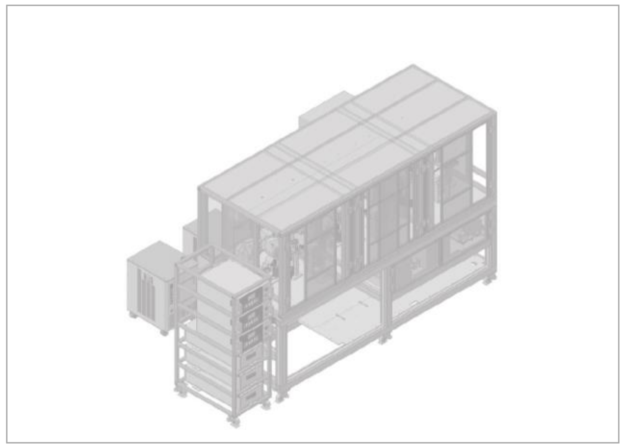




Beam Shaping Test

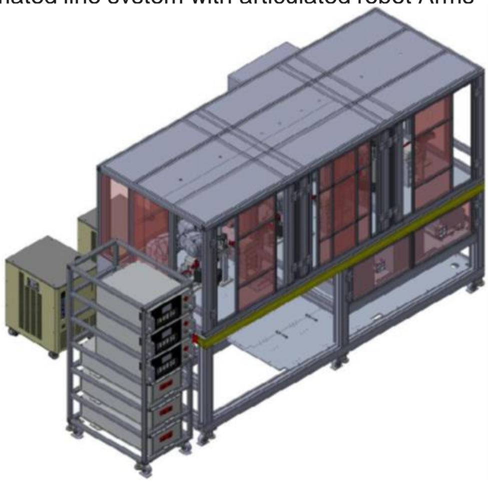
Long Term Stability Test

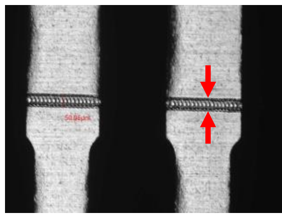
PEEL OF SYSTEM



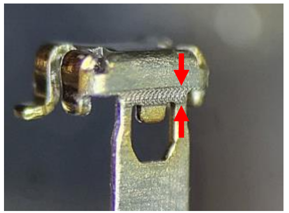
Peel Off System - Introduction

- The system that separates the Au and Ni layers of connectors with an RTR logistics device using a laser
- Optimized Optical system for Peel Off : Long DOF optical system / Co-axial Vision with Fiber opitcs
- Fully automated line svstem with articulated robot Arms

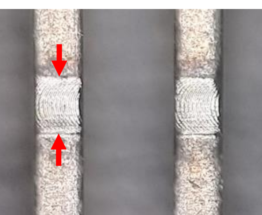




Nickel-Chrome coating
(50㎛ line width)



Nickel-Gold coating
(100㎛ line width)



Nickel-Chrome coating
(200㎛ line width)

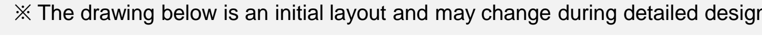
Machine Key Specification

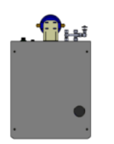
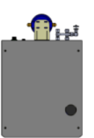
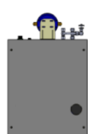
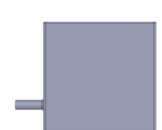
Material	Substrate		Metal material (TBD)
	Std. Substrate Size		400mm x 500mm (TBD) (not limited in work size)
System	Std. System Size		2,820(W) * 1,100(D) * 1,956(H) (TBD)
	System Weight		Approx. 3,500kg
	System Pass Line		1,000mm±50mm (TBD)
	Subst. Load/Unload		Manual Loading (TBD) – Auto available
	Movement method		Roll to Roll
	RTR Flatness		± 200um
	Max Process Speed		100mm/s
	Process Width		50~200㎛
	Vision Align	Camera	1,024 X 768mm
		FOV	4.8 X 3.6mm
		Resolution	< 3.0 um
	Laser Source		Optimizing your applications.
	System Control		Laser + Vision + UI + Sequence control _ PC

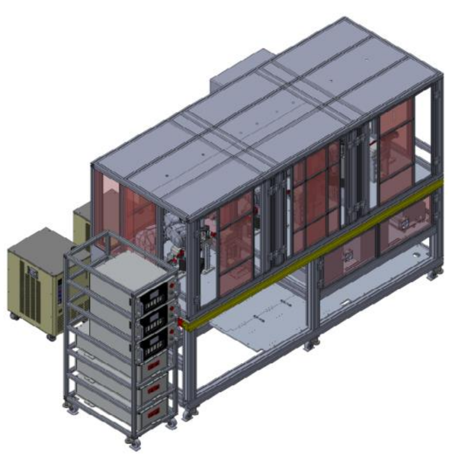
※ The above specification is changed at the request of the customer.

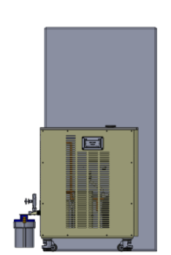
Peel Off System - Lay Out

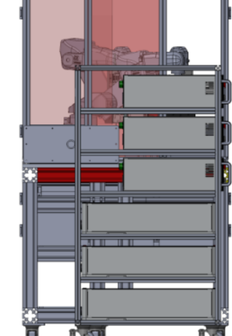
System Lay Out	Main System Size	2,820(W) x 1,100(D) x 1,956(H)
	Chiller	430(W) x 700(D) x 580(H)
	Laser Rack Mount Size	491(W) x 780(D) x 1,530(H)
	Dust Collector	520(W) x 542(D) x 855(H)









Peel Off System - Composition

Vison LCD (6EA)
(for each door)

Chiller for laser 3EA
(1.7KW Air Cool)

Dust Collector 1EA
(Filter Spec. TBD)

Robot Controller (6EA)

Bottom Frame / Cover(option)
(Detail opticions - TBD)

Laser Controller (3EA)
(Front Touch Panel)

Laser Head (3EA)
(Slide Type Rack)

Front/Rea Door
(Door Cover - TBD)
(viewport size - TBD)

Peel Off System - Coaxial Vision Module

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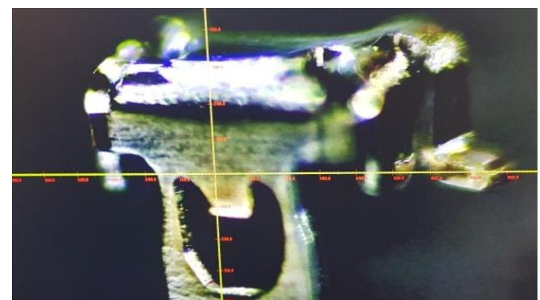
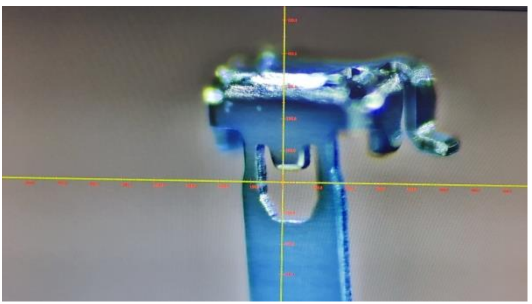
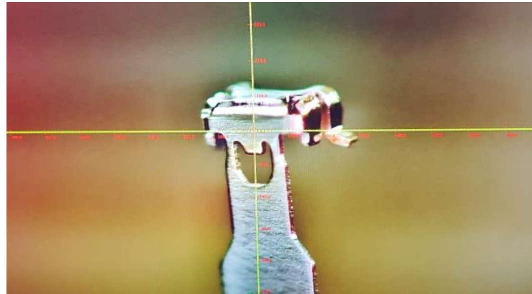
- Developed for application optimization, high stability and improved process reliability
- Magnification, FOV, and various functions can be added according to customer needs



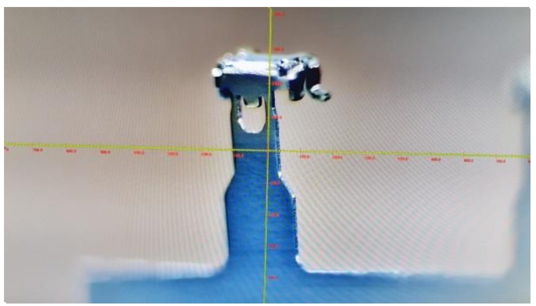
FoV : 2 x 1.2



FoV : 3.2 x 1.9

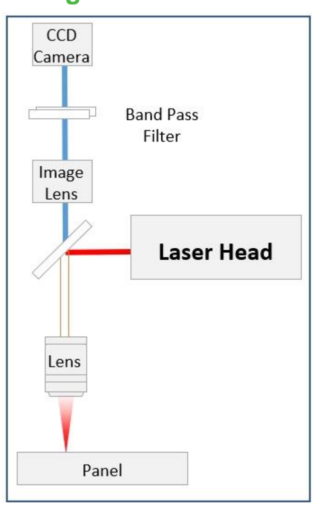


FoV : 5.3 x 3



FoV : 7.1 x 4

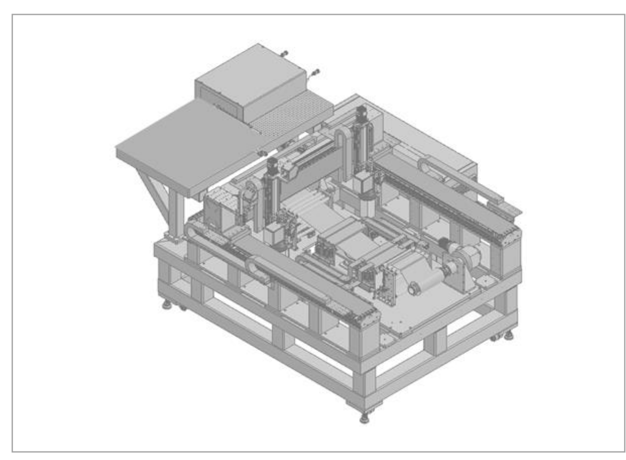
The diagram of coaxial vision



Key Specification

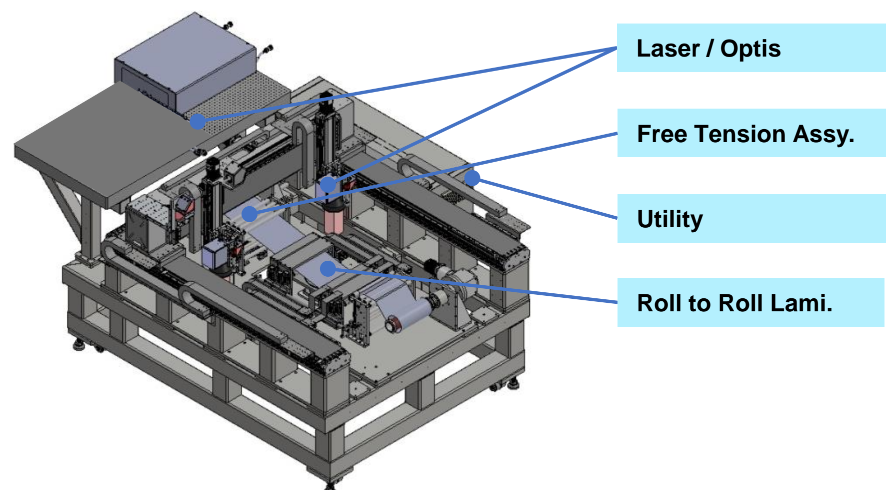
Camera	75x60x39mm (LxWxH) _ 1/3” CMOS
FOV	Variable (2x1.2mm ~ 7.1x4mm_software)
Resolution	< 3.0 um

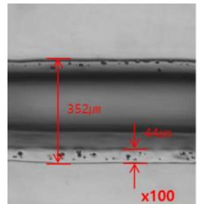
WAFER BG TAPE FREE LAMI.
& LASER CUTTING SYSTEM

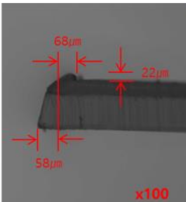


Wafer BG Tape Free LAMI & Laser Cutting System - Introduction

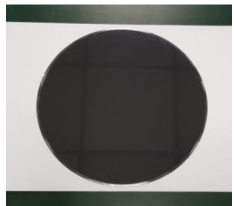
- Free Tension Lamination of Wafer Back Grinding Film
- Laser cutting of film - Offset can be set freely from the wafer edge







BG Tape Cutting



BG Tape Lamination

8" Wafer Sample

Machine Key Specification

Material	Substrate		Films / PCB / Glass / any sheet type subst.
	Std. Substrate Size		8"~12" Wafer
System	Std. System Size		2,500(W) * 2,600(D) * 1,600(H) (TBD)
	System Weight		Approx. 3,500kg
	System Pass Line		800mm±50mm (TBD)
	Subst. Load/Unload		Manual Loading (TBD) – Auto available
	Movement method		Roll to Roll
	Stage Flatness		± 25um
	Max Process Speed		>200mm/s
	Laser Cutting Accuracy		≤ ±10um
	Vision Align	Camera	1024 X 768mm
		FOV	4.8 X 3.6mm
		Resolution	< 3.0 um
	Laser Source		Optimizing your applications.
	System Control		Laser + Vision + UI + Sequence control _ PC

※ The above specification is changed at the request of the customer.

Wafer BG Tape Free LAMI & Laser Cutting System - Result

Vision Image(1)

Vision Image(4)

①

a

④

②

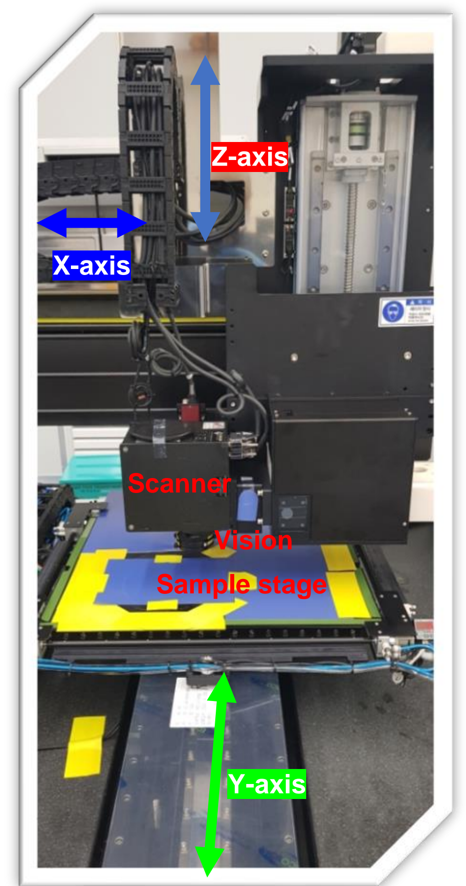
b

③

Vision Image(2)

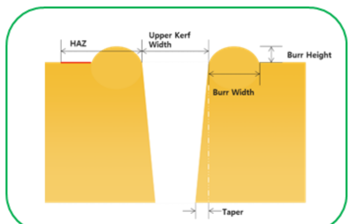
Vision Image(3)

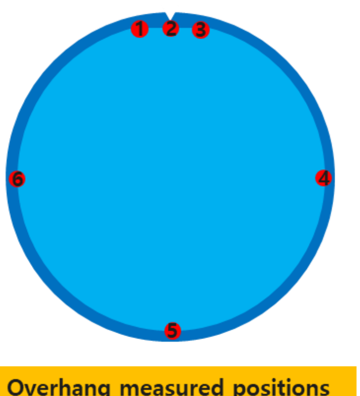
→ Vision Measured Position



Wafer BG Tape Free LAMI & Laser Cutting System - Result

Wafer	Point 1(㎛)	Point 2(㎛)	Point 3(㎛)	Point 4(㎛)	Point 5(㎛)	Point 6(㎛)	Max-Min(㎛)
1	118	128	127	95	97	125	33
2	115	108	120	91	99	104	29
3	115	110	120	90	89	109	31
4	108	113	108	104	103	118	15
5	107	107	106	106	108	113	7
Max-Min(㎛)	**11**	**21**	**21**	**16**	**19**	**21**	





Overhang measured positions

Top View

CO2

UV Pico

UV Nano

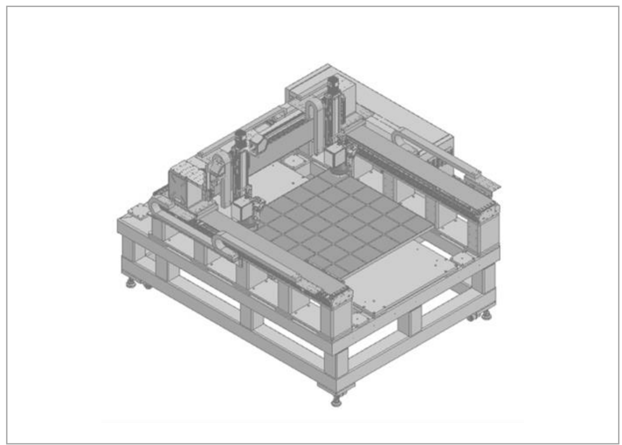
Cross Section View

CO2

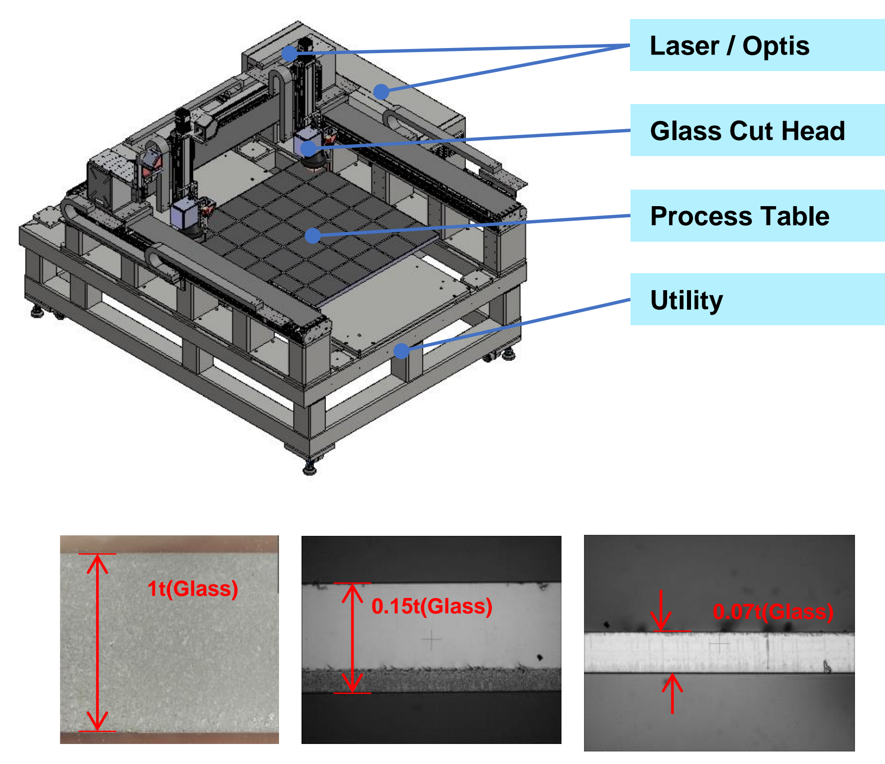
UV Pico

UV Nano

Large Area Glass Cut



Large Area Glass or Film Cut - Introduction



Glass Cutting

Machine Key Specification

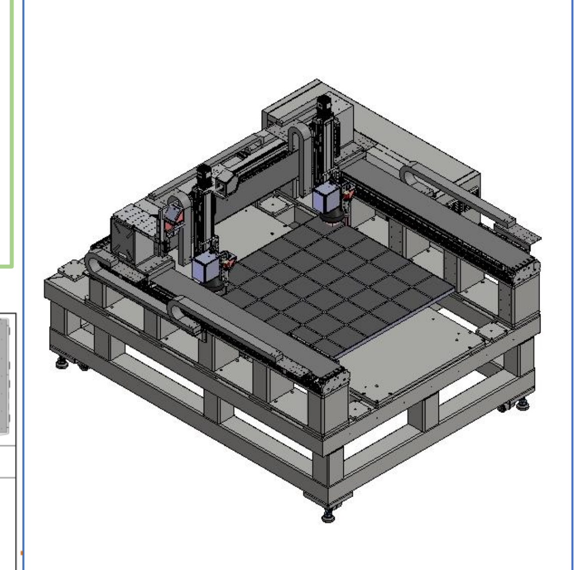
Material	Substrate		Films / PCB / Glass / any sheet type subst.
	Std. Substrate Size		500mm x 500mm (TBD) (not limited in work size)
System	Std. System Size		2,500(W) * 2,600(D) * 1,600(H) (TBD)
	System Weight		Approx. 2,500kg
	System Pass Line		1,000mm±50mm (TBD)
	Subst. Load/Unload		Manual Loading (TBD) – Auto avaiable
	Cutting Station		Pin Hole with Vacuum or Porous
	Stage Flatness		± 25um
	Max Cutting Speed		>200mm/s
	Laser Cutting Accuracy		≤ ±10um
	Vision AI ign	Camera	1024 X 768mm
		FOV	4.8 X 3.6mm
		Resolution	< 3.0 um
	ESD		CDA – Air blow, Anti-ESD coating material
	System Control		Laser + Vision + UI + Sequence control _ PC

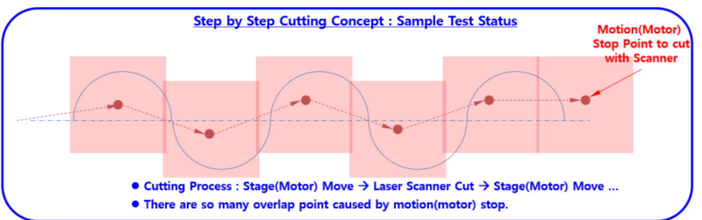
※ The above specification is changed at the request of the customer.

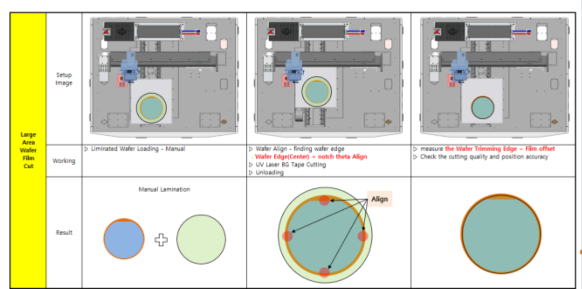
Large Area Glass Cut - MotF Solution (Precision Large Area Laser Solution)

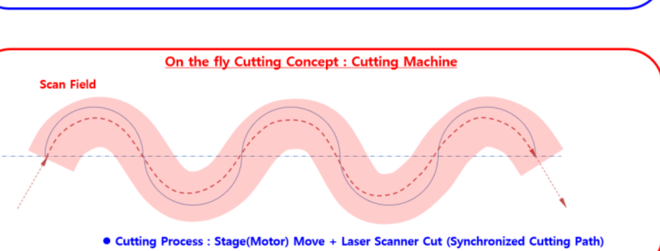
Laser Cut / Patterning / Marking for Large Area MotF

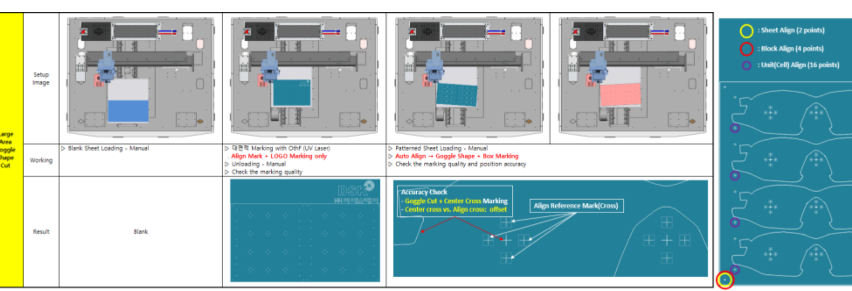
- Used for Large Area Laser Cutting/Patterning/Marking Applications with sheet type various substrates
- Continuous Line Laser processing without size limited
- System Control Type : PC with Laser & Motion Syncrozied Concept
- Fine Alignment Vision & Precision Area Compenstion System : Processing Acuracy < 10um
- The development of the full auto probe station for OLED is completed



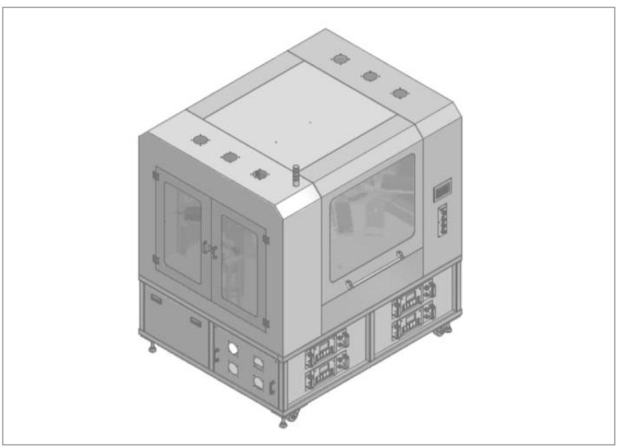








MARKING SYSTEM



Marking System - Introduction

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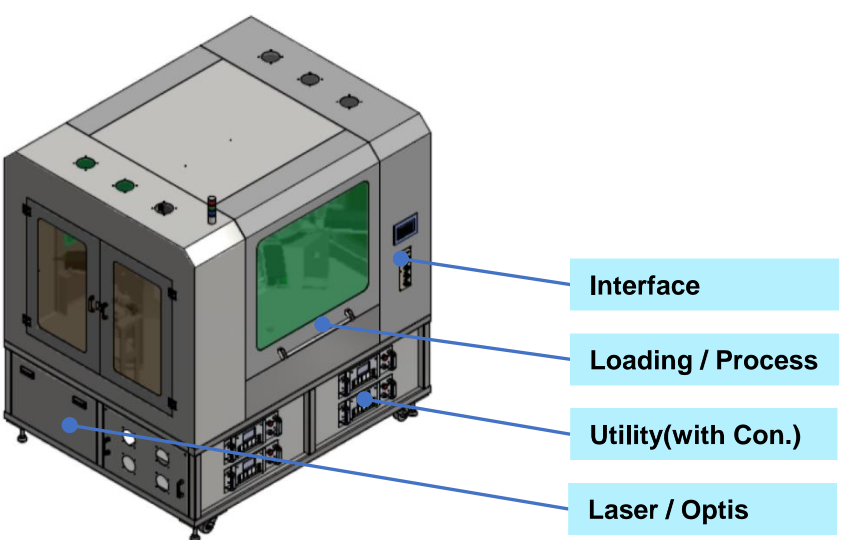
- Marking (Cutting/Patterning) device using various lasers
- Easy maintenance and operation
- Remote control interfaces
- Applicable to various wavelengths/types of laser → Optimized for various material conditions
- Continuous upgrade support



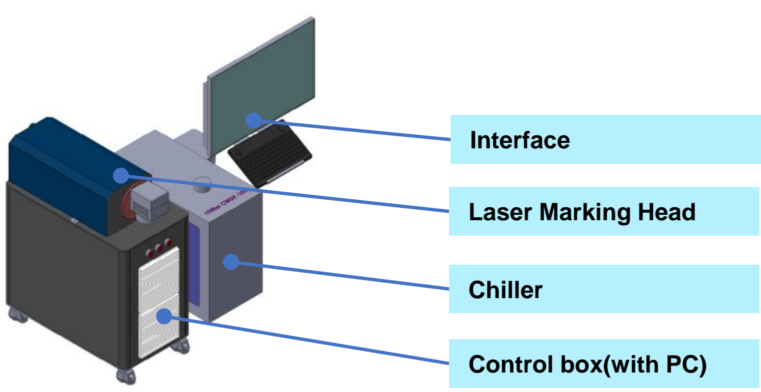
Machine Key Specification

Material	Substrate		Films / PCB / Glass / food container / any sheet type subst.
	Std. Substrate Size		200 * 200mm (TBD)
System	Std. System Size		2,100(W) * 1,800(D) * 2,200(H) (TBD)
	System Weight		Approx. 2,500kg
	System Pass Line		1,000mm±50mm (TBD)
	Subst. Load/Unload		Manual Loading (TBD) – Auto available
	Cutting Station		Pin Hole with Vacuum
	Stage Flatness		± 100um
	Max Marking Speed		500mm/s
	Laser Marking Accuracy		± 100um
	Vision Align	Camera	1024 X 768mm
		FOV	4.8 X 3.6mm
		Resolution	< 3.0 um
	Laser Source		Optimizing your applications.
	System Control		Laser + Vision + UI + Sequence control _ PC

※ The above specification is changed at the request of the customer.

Marking Module - Introduction

- Marking (Cutting/Patterning) device using various lasers
- Easy maintenance and operation
- Remote control interfaces
- Applicable to various wavelengths/types of laser → Optimized for various material conditions
- Continuous upgrade support
- Waterproof IP67/IP 66 Grade of Laser Head – Response to high humidity production environment



Machine Key Specification

Material	Substrate		Films / PCB / Glass / food container / any sheet type subst.
	Std. Substrate Size		200 * 200mm (TBD)
Marker	Water and dust IP ratings		IP 67 / 66 (option)_Laser Head
	Laser Power [W]		20 / 5 / 2
	Wavelength [nm]		1,064 / 532 / 355
	Speed [mm/s]		≤ 500
	M2		<1.5 / 2.0 / <1.2
	Output power stability(typical)[%]		3 / 1 / < 5
	Operating Conditions	Power Supply	220VAC, 60Hz
		Temperature [°C]	15 ~ 35
		Humidity [%]	10 ~ 90
		Cooling	Forced Air Cooling or Water

※ The above specification is changed at the request of the customer.

Marking/Cutting System - Result

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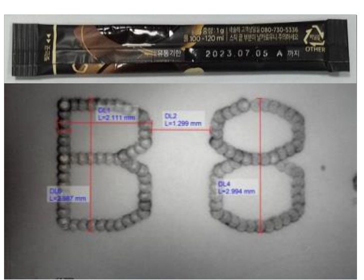
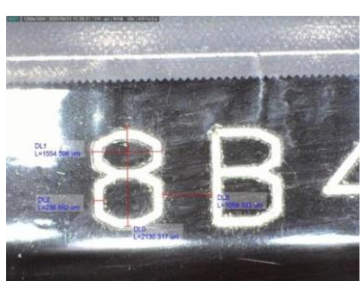
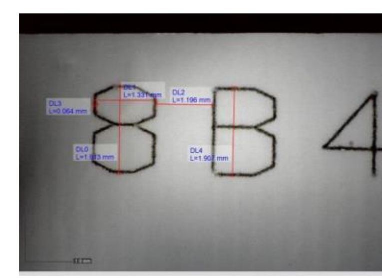
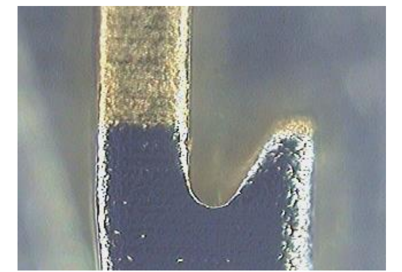
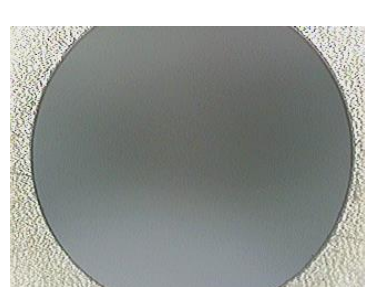
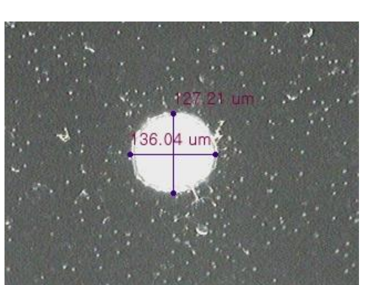
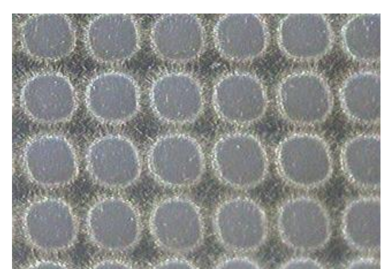
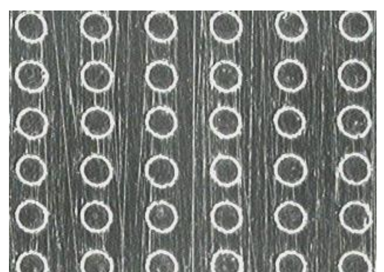







Marking System - Marking Grade

TruCheck Verification - DM8072-6A54CE

45 | 30 | 30 | 30 | 30 | 90

Main | General Characteristic | Data Detail | Quality Detail | Advanced Detail | Histogram

Overall ISO29158 Grade
A (4.0)
DPM 4.0/15/660/45Q

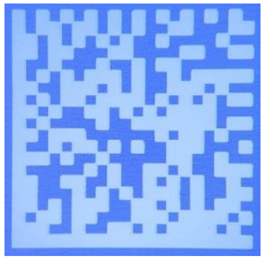
Symbology
DataMatrix

Grade Parameters	
Unused Error Correction (UEC)	100% A
Cell Contrast (CC)	47% A
Cell Modulation (CMOD)	A
Reflectance Margin (RM)	A
Axial Nonuniformity (ANU)	1.4% A
Grid Nonuniformity (GNU)	4.5% A
Fixed Pattern Damage (FPD)	4.0 A
Left 'L' Side (LLS)	A
Bottom 'L' Side (BLS)	A
Left Quiet Zone (LQZ)	A
Bottom Quiet Zone (BQZ)	A
Top Quiet Zone (TQZ)	A
Right Quiet Zone (RQZ)	A
Top Transition Ratio (TTR)	0% A
Right Transition Ratio (RTR)	0% A
Top Clock Track (TCT)	A
Right Clock Track (RCT)	A
Distributed Damage Grade (DDG)	4.0 A
DECODE	A
Minimum Reflectance (MR)	52% A

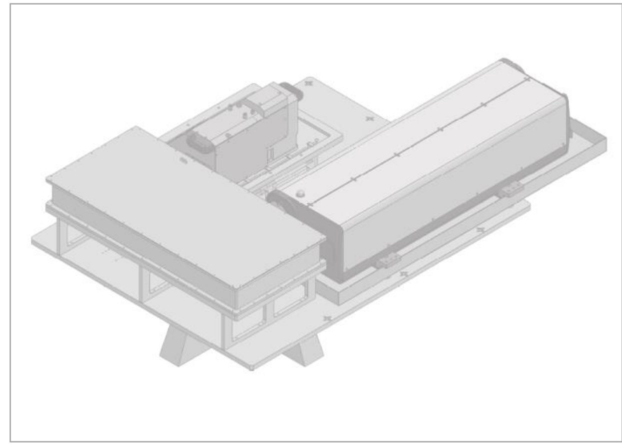
Generic Acceptance Criteria
Pass

Data
alti_high_tech_1234567890

Go Live

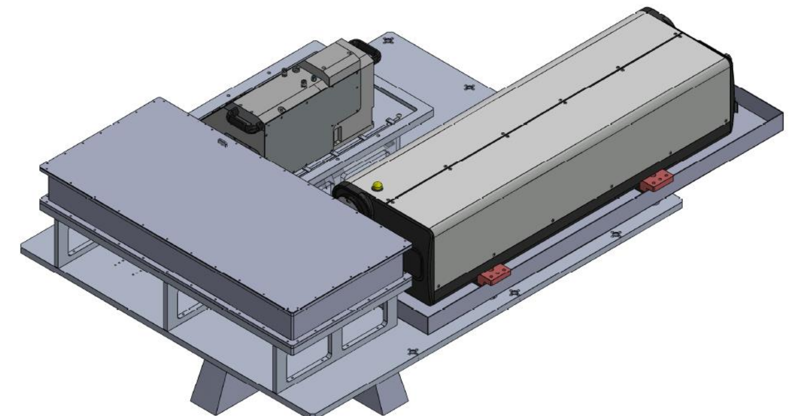


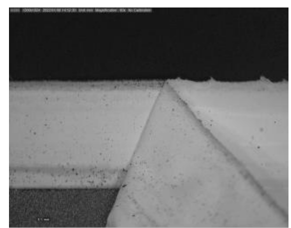
Secondary Battery Separator Laser Cutting Module

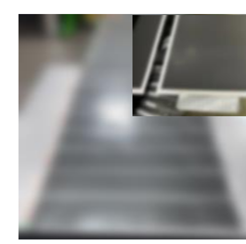


Secondary Battery Separator Cutting System - Introduction

- A machine that cuts high-speed moving battery materials with a laser
- more than 15,000mm/s cutting speeds available





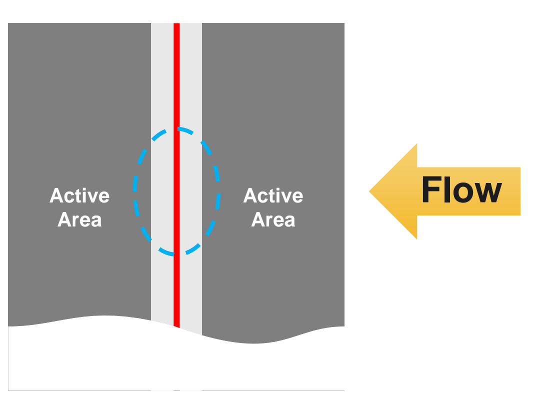


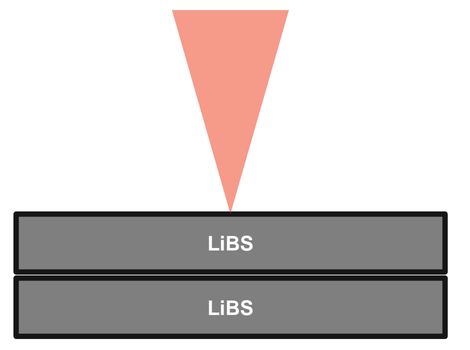
Machine Key Specification

Material	Substrate	Secondary Battery Separator
	Std. Substrate Size	Width 600mm(Movement method : Roll to Roll)
Laser	Wavelength [um]	9.3
	Average power [W]	400
	Repetition rate range [kHz]	0 ~ 100
	Pulse width [us]	2 ~ 400
	Polarization	Linear
Scanner	Wavelength [um]	9.4
	Entrance aperture[mm]	16
	Interface	SL2-100
	Water cooling	3 l/min, p < 4.5 bar
	Weight	35 kg
	Tracking error	< 0,45 ms
	Typical positioning speed	20 rad/s
	Controller board	Scanlab RTC Control boards

※ The above specification is changed at the request of the customer.

Secondary Battery Separator Cutting System - Result

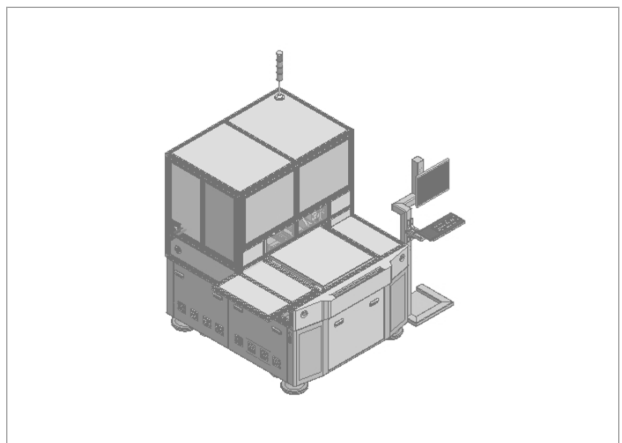




Secondary Battery Separator Cutting System - Result

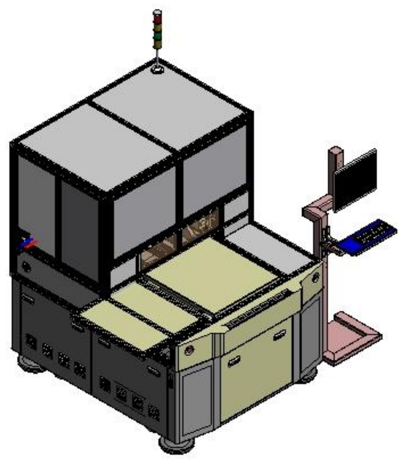
	30kHz	50kHz	100kHz
Top			
Bottom			

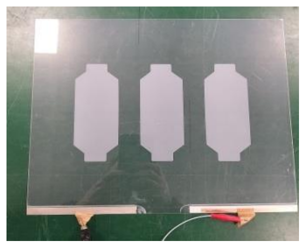
ITO PATTERNING

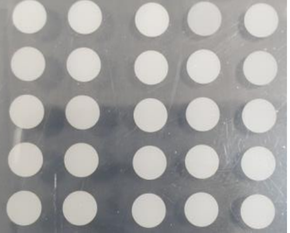


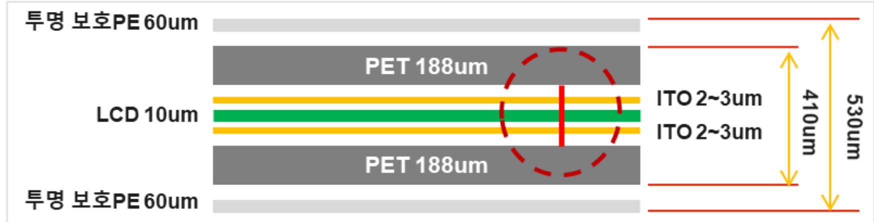
ITO Patterning - Introduction

- Device for ITO Patterning of PDLCD







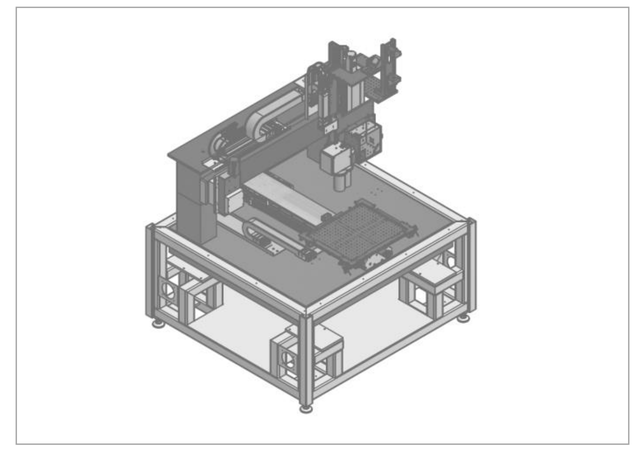


Machine Key Specification

Material	Substrate		PDLCD
	Std. Substrate Size		400 * 400mm (TBD)
System	Std. System Size		1,500(L) * 2,200(W) * 1,900(H)
	System Weight		Approx. 1,500kg
	System Pass Line		1,000mm±50mm (TBD)
	Subst. Load/Unload		Manual Loading (TBD) – Auto available
	Cutting Station		Pin Hole with Vacuum
	Stage Flatness		± 50um
	Max Marking Speed		>500mm/s
	Laser Patterning Accuracy		≤ ±20um
	Vision Align	Camera	1024 X 768mm
		FOV	4.8 X 3.6mm
		Resolution	< 3.0 um
	Laser Source		Optimizing your applications.
	System Control		Laser + Vision + UI + Sequence control _ PC

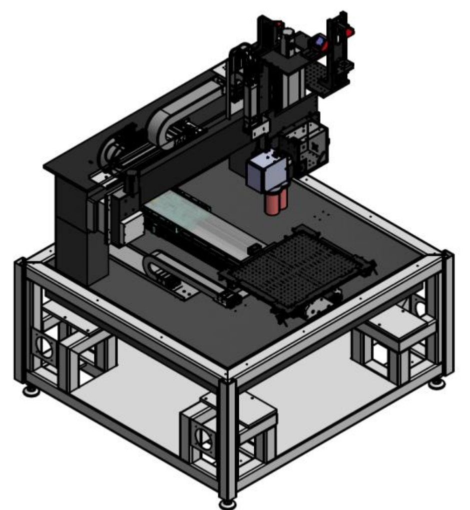
※ The above specification is changed at the request of the customer.

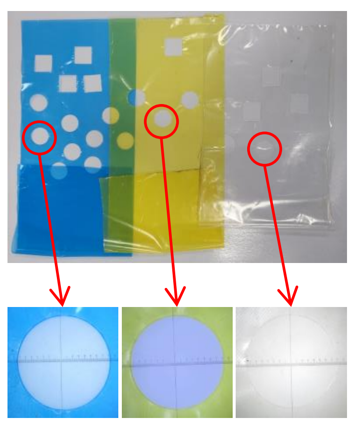
3D FILM CUTTING MODULE

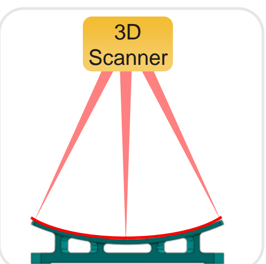


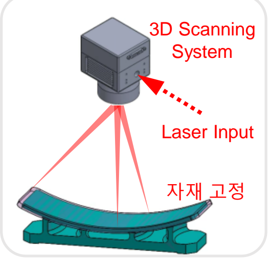
3D Film Cutting - Introduction

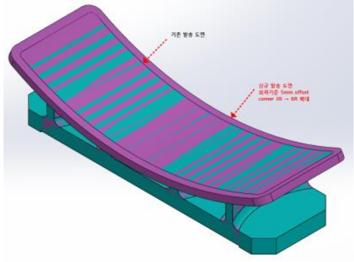
- Laser Cutting the Vairous films attached to the 3D molded glass











Machine Key Specification

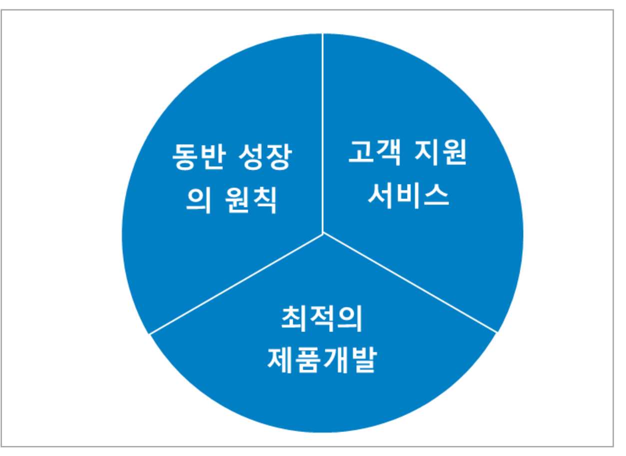
Material	Substrate		Film (with 3D Glass LAMI)
	Std. Substrate Size		400 * 400mm (TBD)
System	Std. System Size		1,500(W) * 1,600(D) * 1,800(H) (TBD)
	System Weight		Approx. 1,500kg
	System Pass Line		1,000mm±50mm (TBD)
	Subst. Load/Unload		Manual Loading (TBD) – Auto available
	Cutting Station		Pin Hole with Vacuum
	Stage Flatness		± 50um
	Max Marking Speed		>500mm/s
	Laser Patterning Accuracy		≤ ±20um
	Vision Align	Camera	1024 X 768mm
		FOV	4.8 X 3.6mm
		Resolution	< 3.0 um
	Laser Source		Optimizing your applications.
	System Control		Laser + Vision + UI + Sequence control _ PC

※ The above specification is changed at the request of the customer.

alti hightech Merits

Shared growth principle

At our core, we prioritize our customers' success because we understand that our own success is dependent on theirs. We strive to foster shared growth with all companies we do business with by creating successful products from the initial stages of development through mass production.



Best customer support

At AlthHightech Co., Ltd., we are dedicated to ensuring our customers' satisfaction and success. To achieve this goal, we are in the process of establishing a comprehensive infrastructure that will provide end-to-end services, including optimal product supply and product utilization support.

Optimal product development

We take pride in our commitment to offering products that align with consumer trends and market demands. Our goal is to provide a diverse range of high-quality products that meet various needs and price points. Additionally, we offer a unique opportunity to select from our laser products, which are developed using AltiHightech's proprietary technology and expertise.

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